L Number	Hits	Search Text	DB	Time stamp
3	334	(increas\$3 rais\$3) with height with solder	USPAT	2004/08/20 11:41
4	26	(increas\$3 rais\$3) with height with solder with material	USPAT	2004/08/20
5	5	((semi\$1conductor adj laser) near3	USPAT	14:06 2004/08/20
		<pre>(plural\$3 multiple several)) and (((integrated mono\$1lithic\$4) with</pre>		14:12
		<pre>(photodetect\$3 detect\$3) with (laser ((light radiation) adj (source emit\$4))))</pre>		
		<pre>same (tracking near3 (signal error detection)) same (focus\$4 near3 (signal</pre>		
	0.57	error detection))) 369/\$7.ccls. and ((focus\$4 near3 (signal	USPAT	2004/08/20
9	957	error)) same (track\$3 near3 (error	USPAI	17:11
10	186	signal)) same (amplifier)) 369/\$7.ccls. and ((focus\$4 near3 (signal	USPAT	2004/08/20
		error)) same (track\$3 near3 (error signal)) same (amplifier)) and ((plural\$3		17:13
		<pre>multiple second) near3 (laser ((light radiation) adj (source emit\$4))))</pre>		
11	8		USPAT	2004/08/20
		signal)) same (amplifier) same ((arithmatic arithmetic) same circuit))		
		and ((plural\$3 multiple second) near3		
	_	<pre>(laser ((light radiation) adj (source emit\$4))))</pre>		
12	5	369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error	USPAT	2004/08/20 17:17
		signal)) same (amplifier) same   ((arithmatic arithmetic) adj circuit))		
		and ((plural\$3 multiple second) near3 (laser ((light radiation) adj (source		
13	18	emit\$4))))	USPAT	2004/08/20
	10	error)) same (track\$3 near3 (error signal)) same (amplifier) same	,	17:42
1.6	20	((arithmatic arithmetic) adj circuit))	USPAT	2004/08/20
16	20	(semiconductor adj laser) with substrate)		18:01
21	0	369/\$7.ccls. and (stress\$3 with (relax\$3 reduc\$4 lower\$3 compensat\$3) with	USPAT	2004/08/20 18:02
22	0	(semiconductor adj laser) with substrate) 369/\$7.ccls. and (stress\$3 with	USPAT	2004/08/20
23	7	(semiconductor adj laser) with substrate) 369/\$7.ccls. and (stress\$3 with (laser	USPAT	18:04 2004/08/20
		((light radiation) adj (source emit\$4))) with substrate)		18:04
-	3	tokuda-masahide.in.	US-PGPUB	2004/08/20
-	31	substrate and mount\$3 and solder\$3 and ((first second plural\$3 multiple) with	EPO; JPO; IBM TDB	2004/07/28
_	9	(electrode contact)) and height	EPO; JPO;	2004/07/28
		((first second plural\$3 multiple) with (electrode contact)) and height and	IBM_TDB	11:08
		((optical semi\$1conductor\$1 laser light)		
		near3 (head pick\$lup (pick adj up) device source))	Hanne	2004/07/22
-	1	volume) and 369/\$7.ccls.	USPAT; US-PGPUB	2004/07/28
-	1	(solder\$3 with volume) and 369/\$7.ccls.	USPAT; US-PGPUB	2004/07/28 11:26
_	720	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and ((optical	USPAT; US-PGPUB	2004/07/28 11:26
		semi\$1conductor\$1 laser light) near3 (head pick\$1up (pick adj up) device		
	_	source))		

•				
<del>-</del>	147	(solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
		(solder\$3 with volume) and (((optical	US-PGPUB	11:27
		semi\$1conductor\$1 laser light) near3		
		(head pick\$lup (pick adj up) device		
		source)) same substrate same mount\$3 same		
		solder\$3)		1
_	137	(solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
		(solder\$3 with volume) and (((optical	US-PGPUB	11:28
		semi\$1conductor\$1 laser light) near3		
		(head pick\$lup (pick adj up) device		
1		source)) same substrate same mount\$3 same		
		solder\$3) and (contact electrode)		
_	96	(solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
		(solder\$3 with volume) and (((optical	US-PGPUB	11:29
		semi\$1conductor\$1 laser light) near3		
		(head pick\$1up (pick adj up) device		
		source)) with mount\$3) same substrate		
		same solder\$3) and (contact electrode)		
	75	(solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
	/5	(solder\$3 with volume) and (((optical	US-PGPUB	11:29
		semi\$1conductor\$1 laser light) near3	05 10105	11.23
	1	(head pick\$lup (pick adj up) device		
		source)) with mount\$3 with substrate)		
		same solder\$3) and (contact electrode)		
1_	51	(solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
-	21	(solder\$3 with (neight thick\$4)) and ((solder\$3 with volume) and (((optical	USPAT; US-PGPUB	11:29
		(solder\$3 with volume) and (((optical semi\$1conductor\$1 laser light) near3	03-16100	11.29
		(head pick\$1up (pick adj up) device source)) with mount\$3 with substrate with		
1		source;   with mounts with substrate With		]
		solder\$3) and (contact electrode)	IICDAM.	3004/08/03
-	23	(solder\$3 with (height thick\$4)) and	USPAT;	2004/08/02
		(solder\$3 with volume) and ((((optical	US-PGPUB	14:17
1		semi\$1conductor\$1 laser light) near3		
1		(head pick\$lup (pick adj up) device		
1		source)) with mount\$3 with substrate with		[ ]
		solder\$3) same (contact electrode))		]
-	1	20030147333.pn.	USPAT;	2004/08/02
1			US-PGPUB	14:17
-	930	228/180.22.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	687	228/180.1.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	775	228/180.21.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	287	228/245.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	380	228/246.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	758	228/254.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	1412	257/737.ccls.	USPAT;	2004/08/05
		·	US-PGPUB	13:51
-	1318	257/738.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:51
-	5249	228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
1		228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:06
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
		257/738.ccls.		<u> </u>
-	4520	l	USPAT	2004/08/05
1		228/180.21.ccls. 228/245.ccls.		13:51
		228/246.ccls. 228/254.ccls. 257/737.ccls.		1
		257/738.ccls.		
-	3742	(228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
	3,42	228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:07
1		228/246.ccls. 228/254.ccls. 257/737.ccls.		- • • • •
1		257/738.ccls.) and (step\$3 notch\$2		
1		groov\$2)	1	
	1		USPAT;	2004/08/05
_	, ,,	\&&U/IUU.&&.UUI3. &&U/IUU.I.UUI3.		
-	383	228/180 21 ccls 228/245 ccls	IIS-DCDIID	1 14 • 07
-	383	228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:07
-	383	228/246.ccls. 228/254.ccls. 257/737.ccls.	US-PGPUB	14:07
-	383		US-PGPUB	14:07

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-	110	(228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
		228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:09
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
		257/738.ccls.) and ((step\$3 notch\$2		
		groov\$2) same optical)		
	242			0004/00/05
-	343	(228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
		228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:10
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
		257/738.ccls.) and ((step\$3 notch\$2		
		groov\$2) same (optical laser ((light		
		radiation) adj (source emit\$4))))		
	206	(228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
-	206			
		228/180.21.ccls. 228/245.ccls.	US-PGPUB	15:02
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
		257/738.ccls.) and ((step\$3 notch\$2		
		groov\$2) with (optical laser ((light		
		radiation) adj (source emit\$4))))		
_	17	5283446.URPN.	USPAT	2004/08/05
				14:15
1_	189	((step\$3 notch\$2 groov\$2) with (optical	USPAT;	2004/08/05
-	109		· ·	
		laser ((light radiation) adj (source	US-PGPUB	15:03
		emit\$4)))) same substrate same solder\$3		]
	· · · · · · · · · · · · · · · · · · ·	same (contact electrode)		
-	189	((stepped step notch notched groove	USPAT;	2004/08/05
	'	grooved) with (optical laser ((light	US-PGPUB	15:04
		radiation) adj (source emit\$4)))) same		
		substrate same solder\$3 same (contact		
		electrode)		
1_	145	((stepped step notch notched groove	USPAT;	2004/08/05
-	145			1
		grooved) with (optical laser ((light	US-PGPUB	15:05
		radiation) adj (source emit\$4)))) same		
		substrate same solder\$3 same (contact		
		electrode same (align\$4 positioning))		
_	143	((stepped step notch notched groove	USPAT;	2004/08/05
		grooved) with (optical laser ((light	US-PGPUB	15:05
		radiation) adj (source emit\$4)))) same		
		substrate same solder\$3 same (contact		
		electrode same ((align\$4 positioning)		1
		with (optical laser ((light radiation)		
		adj (source emit\$4)))))		
-	97	((stepped step notch notched groove	USPAT	2004/08/05
		grooved) with (optical laser ((light		16:46
		radiation) adj (source emit\$4)))) same		
		substrate same solder\$3 same (contact	[	
		electrode same ((align\$4 positioning)		
		with (optical laser ((light radiation)		
			1	
		adj (source emit\$4)))))		2004/00/05
-	40	YAMADA-TAKAO.in.	USPAT	2004/08/05
			1	15:32
-	610	YAMADA-TAKAO.in.	USPAT;	2004/08/05
			EPO; JPO	15:33
_	51	YAMADA-TAKAO.in. and laser	USPAT;	2004/08/05
1			EPO; JPO	15:33
_	45	YAMADA-TAKAO.in. and laser and nichia.as.	USPAT;	2004/08/05
1-	45	IMMADA-IARAO.III. and laser and hichla.as.		1 ' ' 1
1		/172	EPO; JPO	15:40
-	347	(gallium adj nitride) with laser	USPAT	2004/08/05
				15:40
-	29	((gallium adj nitride) with laser) and	USPAT	2004/08/05
	1	solder\$3		15:47
_	143	solder with (stud adj bump)	USPAT	2004/08/05
	133	Dozacz wzon (boad da) samp,		15:48
	44	and domestich (area and booms and waters)	HCDAM	1
-	14	solder with (stud adj bump adj method)	USPAT	2004/08/05
	1			15:48
-	5	,	USPAT	2004/08/05
	1	"6015979"   "6274891").PN.		16:07
		· · · · · · · · · · · · · · · · · · ·	· · · · · · · · · · · · · · · · · · ·	

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_	26	((mounting bonded bonding mounted	USPAT	2004/08/05
		attaching attached soldering soldered)		17:08
		with (laser ld ((light radiation) adj		
		(source emit\$4))) with (substrate		
		sub\$1mount mount)) same solder\$3 same		
		electrode same ((align\$4 positioning)		
		with (optical laser ((light radiation)		
		adj (source emit\$4))))		
_	0	tokukaihei.in.	USPAT;	2004/08/05
		COMMANNET.III.	EPO; JPO	17:08
	1	07235729.pn.	JPO	2004/08/17
-	1	07233729.pm.	JPO	
	140000	(-1	110000	14:18
-	140900	(plural\$3 multiple two several second)	USPAT	2004/08/17
		with (laser ((light radaition) adj		14:19
		(source emit\$4)))		1
-	2359	(plural\$3 multiple two several second)	USPAT	2004/08/17
		with (laser ((light radaition) adj		14:20
		(source emit\$4))) with (mount\$3 solder\$3		
		disposed) with (substrate)		
_	706	(plural\$3 multiple two several second)	USPAT	2004/08/17
		with (laser ((light radaition) adj		14:21
		(source emit\$4))) with (mount\$3 solder\$3		1
		disposed) with (substrate) with		
		semiconductor		
_	156		USPAT	2004/08/17
		with (laser ((light radaition) adj		14:29
		(source emit\$4))) with (mount\$3 solder\$3		
		disposed) with (substrate) with		ĺ
		semiconductor with electrode		
_	9		USPAT	2004/08/17
_		near3 (laser ((light radaition) adj	OSPAT	14:22
		(source emit\$4)))) with (mount\$3 solder\$3		14.22
		disposed) with (substrate) with		
	1			
		semiconductor) same (electrode near3		
		(plural\$3 multiple))		0004/00/17
-	15	((plural\$3 multiple two several second)	USPAT	2004/08/17
		with (laser ((light radaition) adj		14:25
		(source emit\$4))) with (mount\$3 solder\$3		
		disposed) with (substrate) with		
		semiconductor) same electrode same		
		(solder\$3)		
_	32		USPAT	2004/08/17
		near2 (laser ((light radaition) adj		14:30
		(source emit\$4)))) with (mount\$3 solder\$3		
		disposed) with (substrate) with	1	
		semiconductor with electrode		
_	2		USPAT	2004/08/17
		near2 (laser ((light radaition) adj		14:30
		(source emit\$4)))) with (mount\$3 solder\$3		
	1	disposed) with (substrate) with		
		semiconductor) same electrode same	1	
		solder\$3		
		1 00140140	1	1